

WHAT IS CLAIMED IS:

1. An injection mold for injection molding an encapsulation material to encapsulate at least one integrated circuit chip, said injection mold comprising:

at least two parts that define at least one injection circuit, the injection circuit including:

at least one injection cavity for housing the chip;

at least one transfer chamber from which the encapsulation material is injected; and

at least one injection channel connecting the transfer chamber to the injection cavity; and

at least one blind complementary channel communicating with the injection circuit, the blind complementary channel being formed between the two parts of the mold and forming at least one appendage of encapsulation material that is connected to the encapsulation material that fills the injection circuit.

2. The injection mold according to claim 1, wherein the complementary channel extends from the injection channel.

3. The injection mold according to claim 2, wherein the complementary channel connects two injection channels that are connected to the transfer chamber, and extends some distance from the transfer chamber.

4. The injection mold according to claim 1, wherein the complementary channel connects two injection channels, the two injection channels being connected to the transfer chamber.

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9. A method for injection molding an encapsulation material to encapsulate at least one integrated circuit chip, said method comprising the steps of:

placing a leadframe supporting the chip in an injection mold having at least one injection circuit that includes at least one injection cavity for housing the chip, at least one transfer chamber from which liquid encapsulation material is injected, and at least one injection channel connecting the transfer chamber to the injection cavity;

injecting the liquid encapsulation material into the injection cavity via the injection channel so that the liquid encapsulation material fills the cavity and at least one blind complementary channel of the injection mold, the blind complementary channel communicating with the injection circuit; and

hardening the liquid encapsulation material so as to form a molded part that includes an integrated circuit package corresponding to the injection cavity and at least one complementary branch of encapsulation material corresponding to the at least one blind complementary channel, the complementary branch of encapsulation material being connected to the hardened encapsulation material filling the injection circuit.

10. The method according to claim 9, wherein the complementary channel extends from the injection channel.

11. The method according to claim 9, wherein the complementary channel connects two injection channels of the mold, the two injection channels being connected to the transfer chamber.

12. The method according to claim 9, wherein the complementary channel extends from the transfer chamber.

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13. The method according to claim 9, wherein the complementary channel extends from the injection cavity.

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